MAZV082D

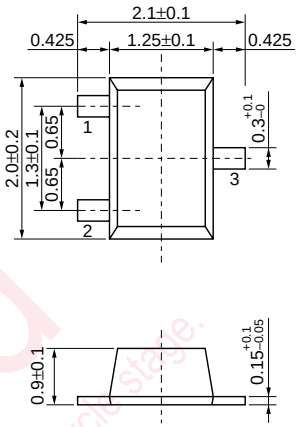
Silicon planer type

Constant voltage, constant current, waveform cripper and surge absorption circuit

■ Features

- S-Mini type package (3-pin)
- Two anode-common wiring of MA8082

Unit : mm



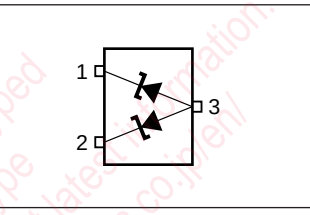
1 : Cathode 1
2 : Cathode 2
3 : Anode 1
Anode 2
Flat S-Mini Type Package (3-pin)

■ Absolute Maximum Ratings (Ta= 25˚C)

Parameter	Symbol	Rating	Unit
Average forward current	$I_{F(AV)}$	100 *1	mA
Instanious forward current	I_{FRM}	200 *1	mA
Total power dissipation	P_{tot}*2	150	mW
Junction temperature	T_j	150	˚C
Storage temperature	T_{stg}	– 55 to + 150	˚C

*1 Working value in a single piece
*2 With a printed-circuit board

■ Internal Connection



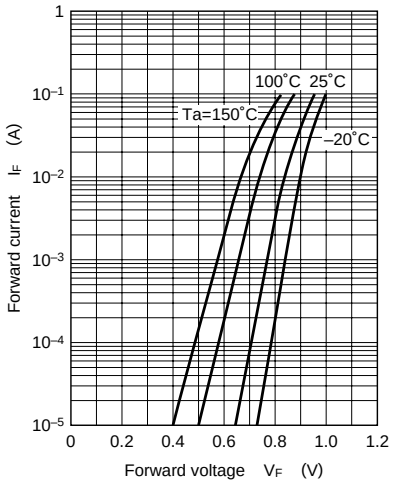
■ Electrical Characteristics (Ta= 25˚C)*1

Parameter	Symbol	Condition	min	typ	max	Unit
Forward voltage	V_F	I_F=10mA		0.9	1.0	V
Zener voltage	V_Z*2	I_Z= 5mA	7.70		8.70	V
Operating resistance	R_{ZK}	I_Z= 0.5mA			120	Ω
	R_Z	I_Z= 5mA			20	Ω
Reverse current	I_R	V_R= 5V			0.1	µA
Temperature coefficient of zener voltage	S_Z*3	I_Z= 5mA		4.6		mV/˚C

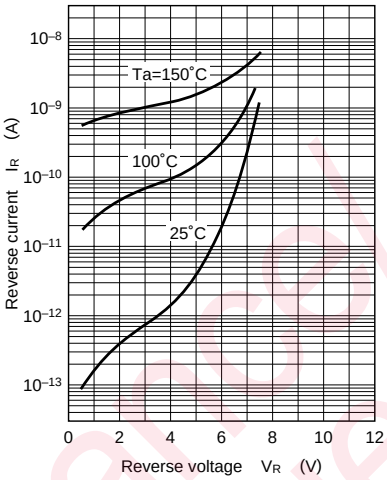
Note 1. Rated input/output frequency : 5MHz
2. * 1 : The V_Z value is for the temperature of 25˚C. In other cases, carry out the temperature compensation.
* 2 : Guaranteeed at 20ms after power application
* 3 : T_j= 25 to 150˚C

■ Marking

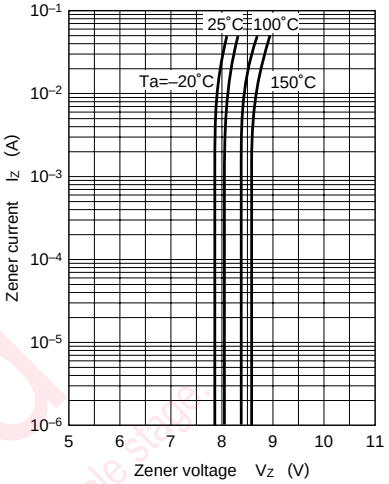
$I_F - V_F$



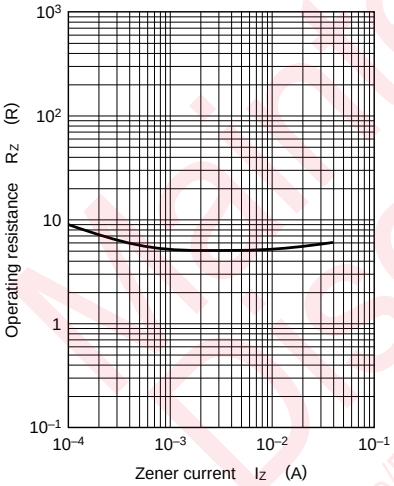
$I_R - V_R$



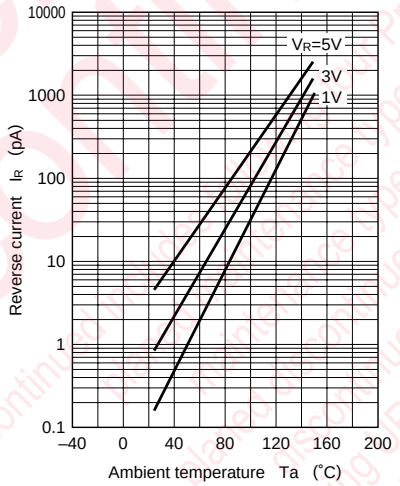
$I_Z - V_Z$



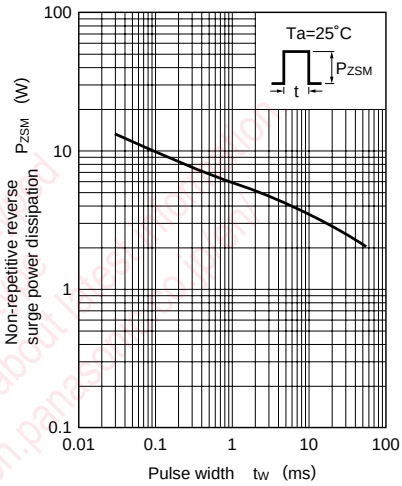
$R_Z - I_Z$



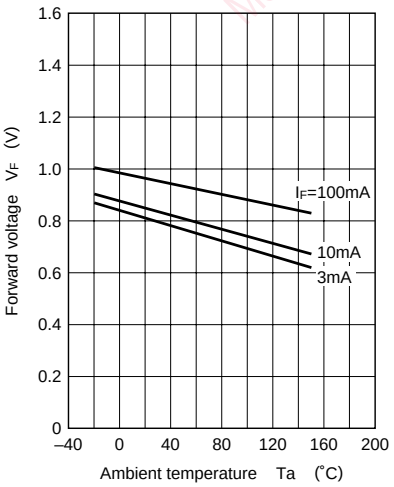
$I_R - Ta$



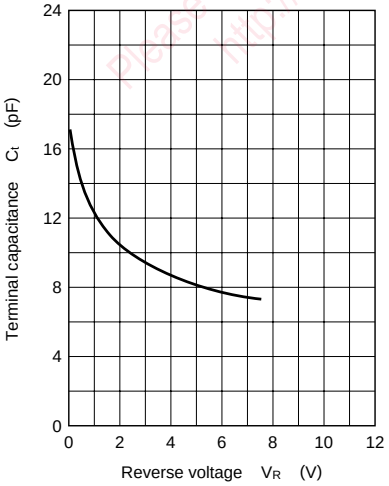
$P_{ZSM} - t_W$



$V_F - Ta$



$C_t - V_R$



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